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Renesas Electronics website: http://www.renesas.com

April 1<sup>st</sup>, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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# DATA SHEET

# MOS FIELD EFFECT TRANSISTOR NP55N03SUG

# **SWITCHING N-CHANNEL POWER MOS FET**

#### **DESCRIPTION**

The NP55N03SUG is N-channel MOS Field Effect Transistor designed for high current switching applications.

# ORDERING INFORMATION

PART NUMBER	LEAD PLATING	PACKING	PACKAGE		
NP55N03SUG-E1-AY Note					
NP55N03SUG-E2-AY Note	Pure Sn (Tin)	Tape 2500 p/reel	TO-252 (MP-3ZK) typ. 0.27 g		

**Note** Pb-free (This product does not contain Pb in external electrode.)

#### **FEATURES**

• Channel temperature 175 degree rated

Low on-state resistance

 $R_{DS(on)} = 5.0 \text{ m}\Omega$  MAX. (Vgs = 10 V, ID = 28 A)

(TO-252)

Low input capacitance

 $C_{iss} = 3500 pF TYP. (V_{DS} = 25 V)$ 



# ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (V <sub>GS</sub> = 0 V)	VDSS	30	V
Gate to Source Voltage (V <sub>DS</sub> = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	I <sub>D(DC)</sub>	±55	Α
Drain Current (pulse) Note1	I <sub>D(pulse)</sub>	±220	Α
Total Power Dissipation (Tc = 25°C)	P <sub>T1</sub>	77	W
Total Power Dissipation (T <sub>A</sub> = 25°C)	P <sub>T2</sub>	1.2	W
Channel Temperature	Tch	175	°C
Storage Temperature	T <sub>stg</sub>	-55 to +175	°C
Repetitive Avalanche Current Note2	IAR	33	Α
Repetitive Avalanche Energy Note2	Ear	109	mJ

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

**2.** T<sub>ch</sub>  $\leq$  150°C, V<sub>DD</sub> = 15 V, R<sub>G</sub> = 25  $\Omega$ , V<sub>GS</sub> = 20  $\rightarrow$  0 V, L = 100  $\mu$ H

#### THERMAL RESISTANCE

Channel to Case Thermal Resistance	Rth(ch-C)	1.95	°C/W
Channel to Ambient Thermal Resistance	Rth(ch-A)	125	°C/W

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90%

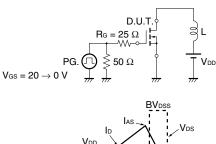
VGS

# **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			1	μA
Gate Leakage Current	Igss	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V			±100	nA
Gate to Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	3.0	4.0	V
Forward Transfer Admittance Note	y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 28 A	10	20		S
Drain to Source On-state Resistance Note	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 28 A		4.0	5.0	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = 25 V,		3500	5300	pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V,		400	600	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		260	470	pF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 15 V, I <sub>D</sub> = 28 A,		32	70	ns
Rise Time	tr	V <sub>GS</sub> = 10 V,		52	130	ns
Turn-off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> = 0 Ω		73	150	ns
Fall Time	tf			12	30	ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = 24 V,		62	93	nC
Gate to Source Charge	Qgs	V <sub>GS</sub> = 10 V,		14		nC
Gate to Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = 55 A		21		nC
Body Diode Forward Voltage Note	V <sub>F(S-D)</sub>	I <sub>F</sub> = 55 A, V <sub>GS</sub> = 0 V		0.92	1.5	V
Reverse Recovery Time	trr	I <sub>F</sub> = 55 A, V <sub>GS</sub> = 0 V,		40		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		34		nC

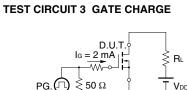
Note Pulsed

# **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

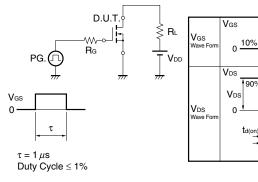




-Starting Tch

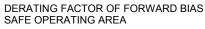


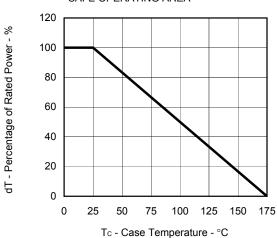
# **TEST CIRCUIT 2 SWITCHING TIME**



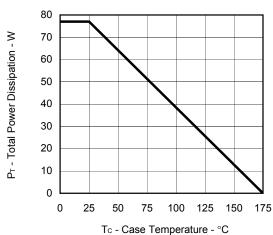
2

# TYPICAL CHARACTERISTICS (TA = 25°C)

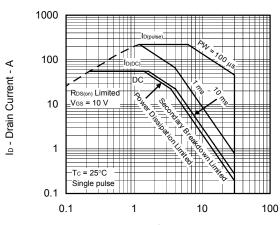




# TOTAL POWER DISSIPATION vs. CASE TEMPERATURE

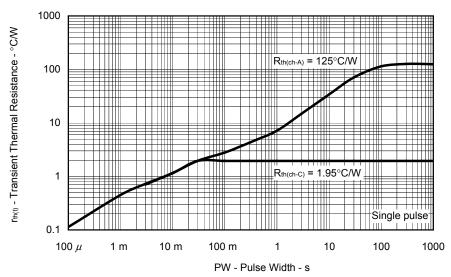


#### FORWARD BIAS SAFE OPERATING AREA

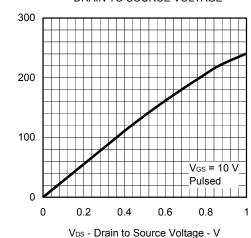


 $V_{\text{\scriptsize DS}}$  - Drain to Source Voltage - V

# TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



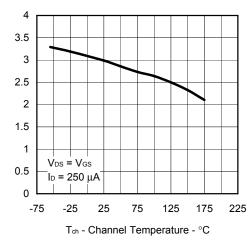
#### DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



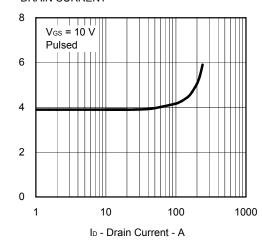
Ip - Drain Current - A

V<sub>GS(th)</sub> - Gate to Source Threshold Voltage - V

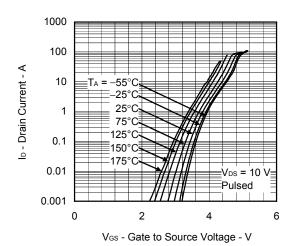
#### GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE



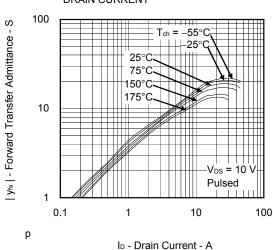
#### DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



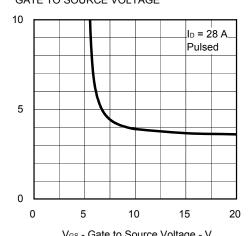
#### FORWARD TRANSFER CHARACTERISTICS



#### FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



#### DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

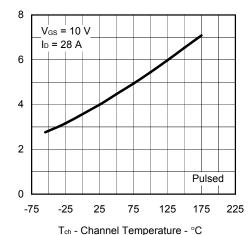


V<sub>GS</sub> - Gate to Source Voltage - V

R<sub>DS(cn)</sub> - Drain to Source On-state Resistance - mΩ

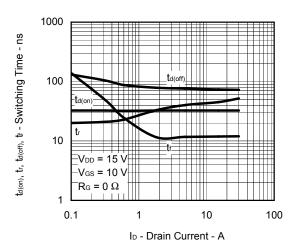
R<sub>DS(ση)</sub> - Drain to Source On-state Resistance - mΩ

DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE

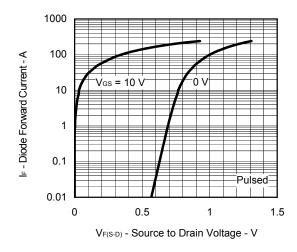


 $\mathsf{R}_{\mathsf{DS}(\varpi)}$  - Drain to Source On-state Resistance -  $m\Omega$ 

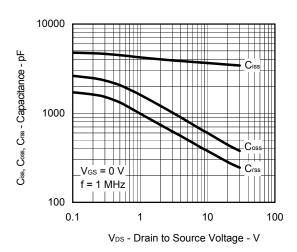
SWITCHING CHARACTERISTICS



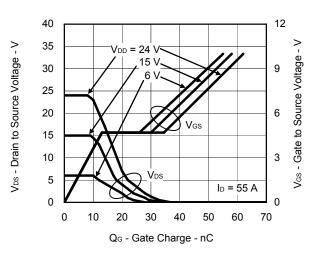
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



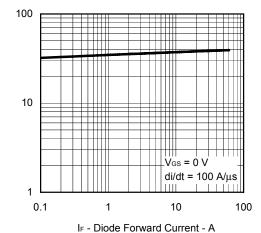
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

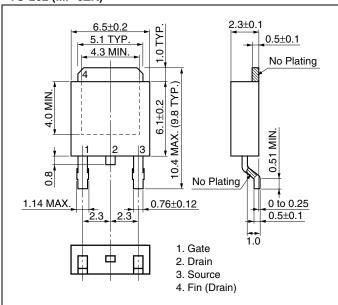


5

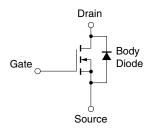
tr - Reverse Recovery Time - ns

# PACKAGE DRAWING (Unit: mm)

# TO-252 (MP-3ZK)



# **EQUIVALENT CIRCUIT**

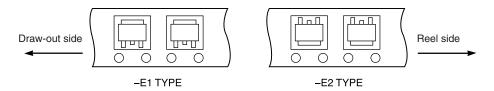


**Remark** Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

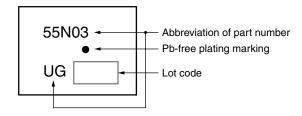
6

# TAPE INFORMATION

There are two types (-E1, -E2) of taping depending on the direction of the device.



#### <R> MARKING INFORMATION



# RECOMMENDED SOLDERING CONDITIONS

The NP55N03SUG should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, please contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (http://www.necel.com/pkg/en/mount/index.html)

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared reflow	Maximum temperature (Package's surface temperature): 260°C or below	IR60-00-3
	Time at maximum temperature: 10 seconds or less	
	Time of temperature higher than 220°C: 60 seconds or less	
	Preheating time at 160 to 180°C: 60 to 120 seconds	
	Maximum number of reflow processes: 3 times	
	Maximum chlorine content of rosin flux (percentage mass): 0.2% or less	
Partial heating	Maximum temperature (Pin temperature): 350°C or below	P350
	Time (per side of the device): 3 seconds or less	
	Maximum chlorine content of rosin flux: 0.2% (wt.) or less	

Caution Do not use different soldering methods together (except for partial heating).

NEC NP55N03SUG

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